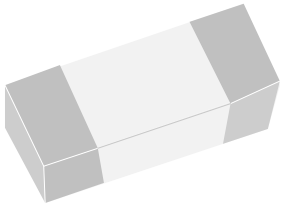
Fast Acting High Current Brick Fuse 5018BC Series

Descriptions

Chip Fuse devices are set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

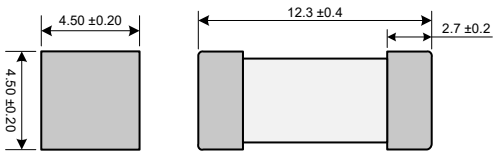
5018BC SMD fuse s for the small size and good electrical performance, reliability and quality.

Electrical Characteristics		
Rated Current	1.0In	2.0In
40A~50A	4 hour minimum	60 sec maximum



Top View (5018BC)

Product Dimensions

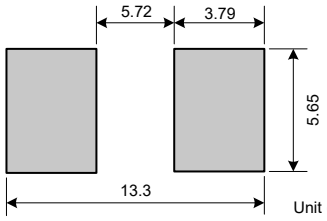


Unit (mm)

Features

- Fast Acting High current brick fuse
- Surface mount deign to save space
- Ceramic Suqare body with end cap
- Designed to UL248-1
- Fully compatible with lead-free solder and high temperature profile associated with lead-free assembly

Recommended land pattern



Unit (mm)

Recommend trace thickness is 3oz, the minimum trace width is 15mm

Electrical information (Tamb=25°C)

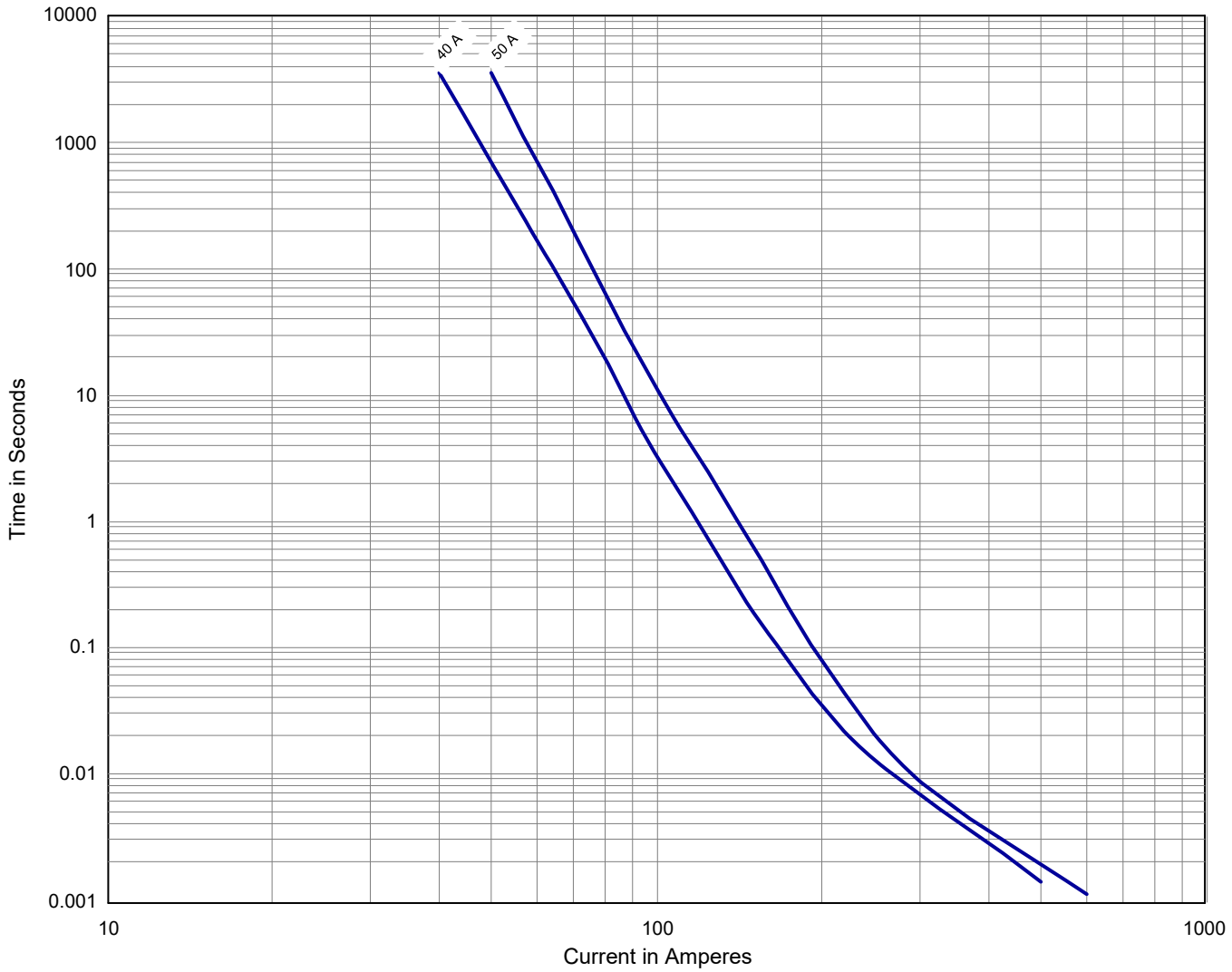
Part number	Rated Voltage		Rated Current	Breaking Capacity * (A)		Typical Cold. Resistance *	Typical Prearcing I^2t *
	AC (V)	DC (V)	(A)	125V AC	DC	(mΩ)	(A^2Sec)
5018BC72-4000	125	72	40	150	500 @72V	1.10	450
5018BC60-5000	-	60	50	-	500 @60V	0.95	600

** AC Interrupting Rating (measured at designated voltage, 100% power factor); DC Interrupting Rating (measured at designated voltage, time constant of less than 50 microseconds, battery source)*

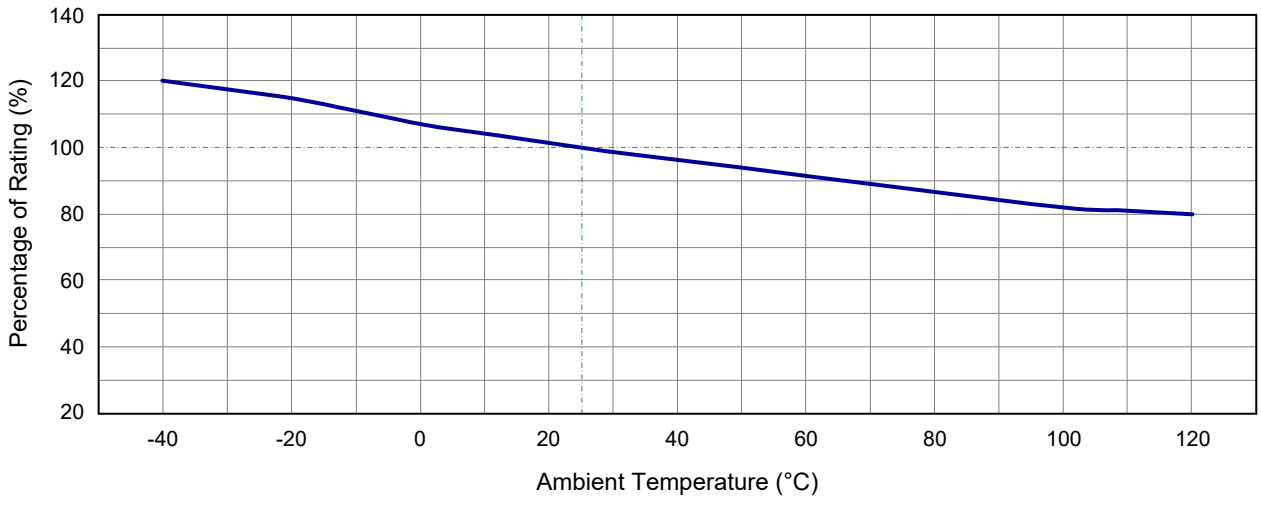
** DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25 ℃*

** Typical Pre-arching I^2t are measured at 10In Current, DC battery bank, but not exceeding the interrupting rating, time constant of calibrated circuit less than 50 microseconds)*

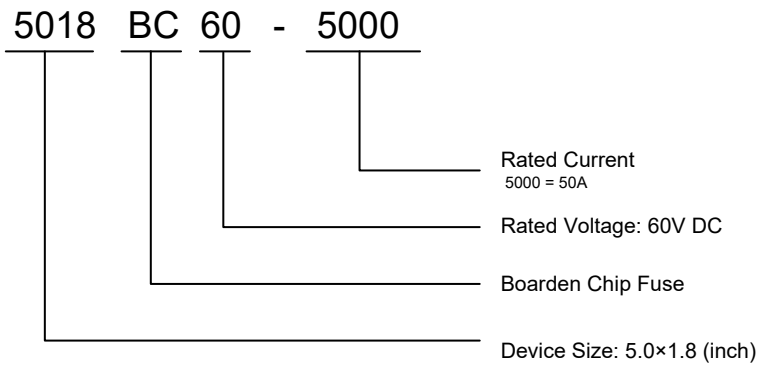
Time-Current Curves



Temperature Derating Curve



Part Numbering System

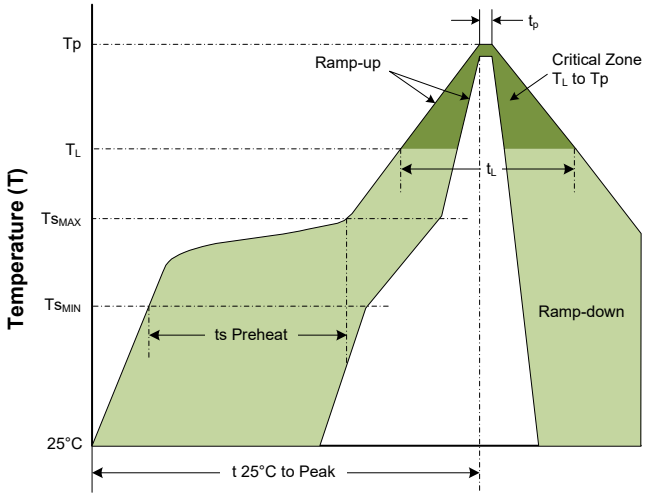


Order Information

Device	Quantity	Reel Size
5018BC Series	1000 pcs	13 Inch

Soldering Parameters

Profile Feature	**Lead-Free Assembly**
Average Ramp-up Rate (Ts_{MAX} to Tp) Average Ramp-down Rate (Tp to T_L)	3°C/second max. 6°C/second max.
Preheat • Temperature Min (Ts_{MIN}) • Temperature Max (Ts_{MAX}) • Time (ts Preheat)	 150°C 200°C 60-180 seconds
Time maintained above: • Temperature (T_L) • Time (t_L)	 217°C 60-150 seconds
Peak/Classification Temperature • Temperature (Tp)	 $260^{+0/-5}$°C
Time within 5°C of actual Peak Time (t_p)	 20-40 seconds
Time 25°C to peak Temperature	8 minutes max
Do not exceed	280 °C



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